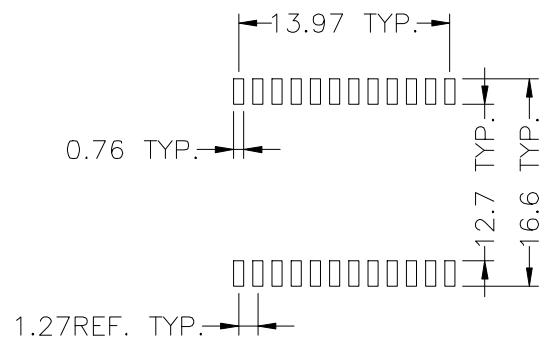
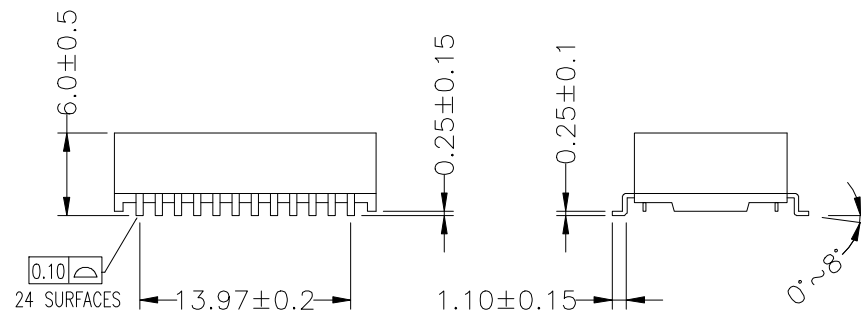
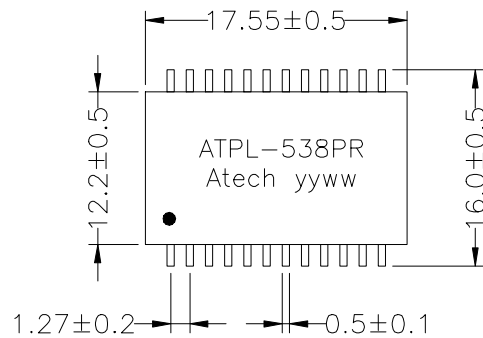
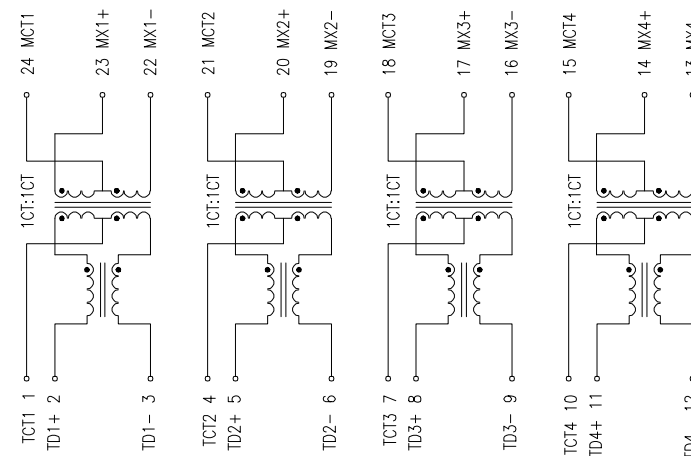




SUGGESTED PAD LAYOUT

CABLE SIDE



CHIP SIDE

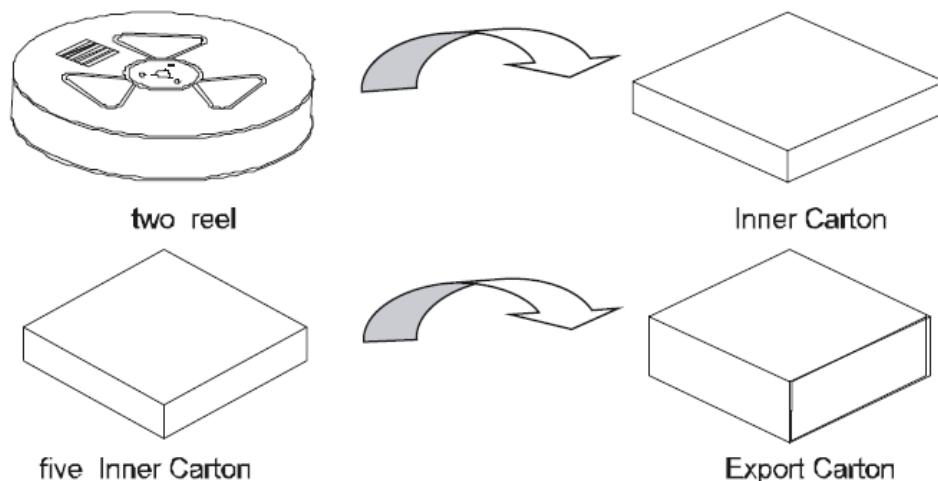
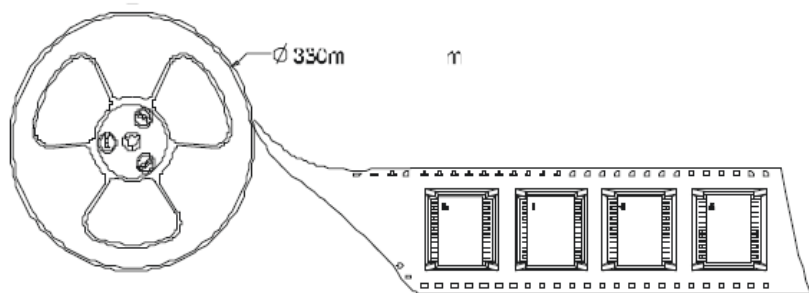
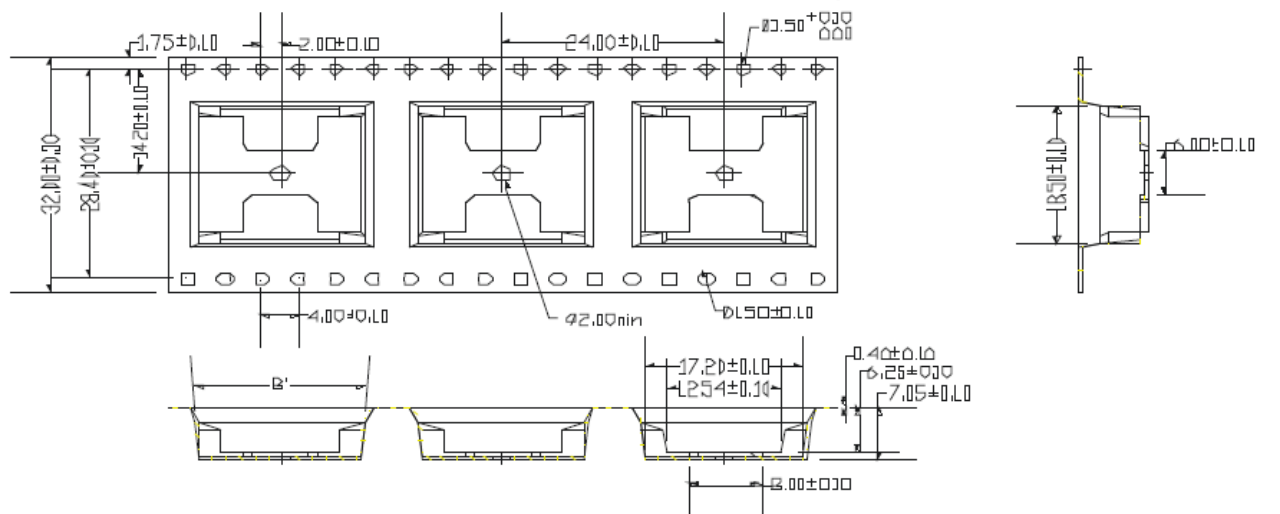
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS@25°C

1. OCL : (@100kHz, 0.1V) : 200uH MIN. WITH 8mA DC BIAS
2. LEAKAGE INDUCTANCE : (@100kHz, 0.1V) : 0.5uH MAX.
3. DCR : 1.0Ω MAX.
4. TURNS RATIO : 1CT : 1CT ±5%
5. INSERTION LOSS : (@1-100MHz) : -1.0dB MAX.
(@100-250MHz) : -2.0dB MAX.
6. RETURN LOSS :
-16dB MIN. @ 1≤f≤40 MHz
-16+10log (f/40)dB MIN @ 40<f≤250 MHz, Where f is in MHz
7. CROSS TALK : (@1-250MHz) : -30dB TYP.
8. COMMON MODE REJECTION : (@1-250MHz) : -30dB TYP.
9. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
10. PoE Support 30W : Each channel support 360mA DC balance current,
Full channels support 720mA DC balance current.
11. OPERATING TEMPERATURE : 0°C TO 70°C
12. STORAGE TEMPERATURE : -25°C TO 125°C

								TITLE	
								2.5G/5G POE TRANSFORMER	
								DWG. NO. ATPL-538PR	
RELEASE		06/08/2020	SHIRLEY	BETTY	BETTY	UNITS:	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	M/M			
						DATE	P/N:		DRAW
REVISIONS						06/08/20		SHIRLEY	

3. Package :



Package Quantity:

One Reel=350Pcs

One Inner Carton=350*2=700Pcs

One Export Carton=700*5=3500Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to T _p)	3°C/second max	3°C/second max
Preheat Temperature Min (T _{smin}) Temperature Min (T _{smax}) Time (T _{smin} to T _{smax}) (ts)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T _L) Time (t _L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T _p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T _p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max